



Abstract

The invention relates to a process for joining substrates having electrical, semiconducting, mechanical and/or optical components, and to a composite element.

The process is to be suitable for the substrates which are to be joined substantially irrespective of material and in particular also for sensitive substrates, is to have a high chemical and physical stability and/or is to produce a hermetic cavity.

According to the invention, a raised frame, in particular formed from anodically bondable glass, is applied by evaporation coating to one of the two substrates in order to serve as a joining element.